

NTMD5836NL

Power MOSFET

40 V, Dual N-Channel, SOIC-8

Features

- Asymmetrical N Channels
- Low $R_{DS(on)}$
- Low Capacitance
- Optimized Gate Charge
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

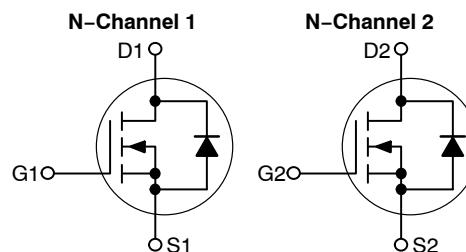
| | $V_{(BR)DSS}$ | $R_{DS(on)}$ Max | I_D Max (Notes 1 and 2) |
|-----------|---------------|-------------------------|------------------------------|
| Channel 1 | 40 V | 12 m Ω @ 10 V | 11 A |
| | | 16 m Ω @ 4.5 V | |
| Channel 2 | 40 V | 20 m Ω @ 10 V | 6.5 A |
| | | 36.5 m Ω @ 4.5 V | |

1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces)
2. Only selected channel is been powered
1W applied on channel 1: $T_J = 1 \text{ W} * 85^\circ\text{C/W} + 25^\circ\text{C} = 110^\circ\text{C}$

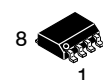


ON Semiconductor®

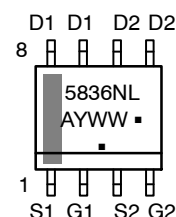
<http://onsemi.com>



MARKING DIAGRAM* AND PIN ASSIGNMENT



SOIC-8
CASE 751



A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping† |
|---------------|---------------------|-----------------------|
| NTMD5836NLR2G | SOIC-8 (Pb-Free) | 2500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

NTMD5836NL

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise stated)

| Parameter | | | Symbol | Ch 1 | Ch 2 | Unit |
|--|------------------------|-----------------------|-----------------------------------|-------------|------|------|
| Drain-to-Source Voltage | | | V _{DSS} | 40 | 40 | V |
| Gate-to-Source Voltage | | | V _{GS} | ± 20 | ± 20 | V |
| Continuous Drain Current R _{θJA} (Notes 3 and 4) | Steady State | T _A = 25°C | I _D | 9.0 | 5.7 | A |
| | | T _A = 70°C | | 7.2 | 4.6 | |
| Power Dissipation R _{θJA} (Notes 3 and 4) | | T _A = 25°C | P _D | 1.5 | 1.5 | W |
| | | T _A = 70°C | | 0.9 | 0.9 | |
| Continuous Drain Current R _{θJA} (Notes 3 and 4) | t ≤ 10s | T _A = 25°C | I _D | 11 | 6.5 | A |
| | | T _A = 70°C | | 8.6 | 4.6 | |
| Power Dissipation R _{θJA} (Notes 3 and 4) | | T _A = 25°C | P _D | 2.1 | 1.9 | W |
| | | T _A = 70°C | | 1.3 | 1.2 | |
| Pulsed Drain Current | t _p = 10 μs | | I _{DM} | 43 | 26 | A |
| Operating Junction and Storage Temperature | | | T _J , T _{STG} | −55 to +150 | | °C |
| Source Current (Body Diode) | | | I _S | 10 | 7.0 | A |
| Single Pulse Drain-to-Source Avalanche Energy (V _{DD} = 40 V, V _{GS} = 10 V, L = 0.1 mH) | | | E _{AS} | 76 | 22 | mJ |
| | | | I _{AS} | 39 | 21 | A |
| Lead Temperature for Soldering Purposes (1/8" from case for 10s) | | | T _L | 260 | | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces)
- Only selected channel is been powered
1W applied on channel 1: $T_J = 1\text{ W} * 85^\circ\text{C/W} + 25^\circ\text{C} = 110^\circ\text{C}$

THERMAL RESISTANCE RATINGS

| Parameter | Symbol | Ch 1 | Ch 2 | Unit |
|--|------------------|------|------|------|
| Junction-to-Ambient Steady State (Notes 5 and 7) | R _{θJA} | 85 | 86 | °C/W |
| Junction-to-Ambient – t ≤ 10 s (Notes 5 and 7) | R _{θJA} | 60 | 65 | |
| Junction-to-Ambient Steady State (Notes 5 and 8) | R _{θJA} | 59 | | |
| Junction-to-Ambient Steady State (Notes 6 and 7) | R _{θJA} | 136 | 136 | |

- Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces)
- Surface-mounted on FR4 board using 0.155 in sq (100 mm²) pad size
- Only selected channel is been powered
1W applied on channel 1: $T_J = 1\text{ W} * 85^\circ\text{C/W} + 25^\circ\text{C} = 110^\circ\text{C}$
- Both channels receive equivalent power dissipation
1 W applied on each channel: $T_J = 2\text{ W} * 59^\circ\text{C/W} + 25^\circ\text{C} = 143^\circ\text{C}$

NTMD5836NL

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | | Ch | Min | Typ | Max | Unit |
|---|---------------------|---|---------------------------|------|-----|-----|-----------|---------------|
| OFF CHARACTERISTICS | | | | | | | | |
| Drain-to-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | | Ch 1 | 40 | | | V |
| | | | | Ch 2 | | | | |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | $V_{(BR)DSS} / T_J$ | | | Ch 1 | | 146 | | mV/ °C |
| | | | | Ch 2 | | 25 | | |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{GS} = 0\text{ V}, V_{DS} = 40\text{ V}$ | $T_J = 25^\circ\text{C}$ | Ch 1 | | | 1.0 | μA |
| | | | | Ch 2 | | | | |
| | | | $T_J = 125^\circ\text{C}$ | Ch 1 | | | 100 | |
| | | | | Ch 2 | | | | |
| Gate-to-Source Leakage Current | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$ | | Ch 1 | | | ± 100 | nA |
| | | | | Ch 2 | | | | |

ON CHARACTERISTICS (Note 9)

| | | | | | | | |
|--|--------------------|---|------|-----|------|------|----------------------|
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = 250\text{ }\mu\text{A}$ | Ch 1 | 1.0 | 1.8 | 3.0 | V |
| | | | Ch 2 | 1.0 | 1.8 | 3.0 | |
| Negative Threshold Temperature Coefficient | $V_{GS(TH)} / T_J$ | | Ch 1 | | 6.0 | | mV/ $^\circ\text{C}$ |
| | | | Ch 2 | | 6.0 | | |
| Drain-to-Source On Resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}, I_D = 10\text{ A}$ | Ch 1 | | 9.5 | 12 | m Ω |
| | | $V_{GS} = 10\text{ V}, I_D = 7\text{ A}$ | Ch 2 | | 16.2 | 20 | |
| | | $V_{GS} = 4.5\text{ V}, I_D = 10\text{ A}$ | Ch 1 | | 13 | 16 | m Ω |
| | | $V_{GS} = 4.5\text{ V}, I_D = 7\text{ A}$ | Ch 2 | | 25.0 | 36.5 | |
| Forward Transconductance | g_{FS} | $V_{DS} = 15\text{ V}, I_D = 10\text{ A}$ | Ch 1 | | 10.5 | | S |
| | | $V_{DS} = 15\text{ V}, I_D = 7\text{ A}$ | Ch 2 | | 6.0 | | |

CHARGES, CAPACITANCES & GATE RESISTANCE

| | | | | | | | |
|------------------------------|------------------|--|------|--|------|--|----|
| Input Capacitance | C _{ISS} | V _{GS} = 0 V, f = 1 MHz, V _{DS} = 20 V | Ch 1 | | 2120 | | pF |
| | | | Ch 2 | | 730 | | |
| Output Capacitance | C _{OSS} | | Ch 1 | | 315 | | |
| | | | Ch 2 | | 123 | | |
| Reverse Transfer Capacitance | C _{RSS} | | Ch 1 | | 225 | | |
| | | | Ch 2 | | 84 | | |

9. Pulse Test: pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$

10. Switching characteristics are independent of operating junction temperatures

NTMD5836NL

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

| Parameter | Symbol | Test Condition | Ch | Min | Typ | Max | Unit |
|-----------|--------|----------------|----|-----|-----|-----|------|
|-----------|--------|----------------|----|-----|-----|-----|------|

CHARGES, CAPACITANCES & GATE RESISTANCE

| | | | | | | | |
|-----------------------|---------------------|---|------|-----|-----|----|----|
| Total Gate Charge | Q _{G(TOT)} | V _{GS} = 10V, V _{DS} = 20V, I _D = 10A | Ch 1 | | 36 | 50 | nC |
| | | V _{GS} = 10 V, V _{DS} = 20 V, I _D = 7 A | Ch 2 | | 16 | | |
| | | V _{GS} = 4.5 V, V _{DS} = 20 V, CH1: I _D = 10 A, CH2: I _D = 7 A | Ch 1 | | 15 | 23 | |
| Ch 2 | | | 8.5 | 11 | | | |
| Threshold Gate Charge | Q _{G(TH)} | | Ch 1 | | 2.4 | | |
| | | | Ch 2 | | 1.0 | | |
| Gate-to-Source Charge | Q _{GS} | | Ch 1 | | 6.9 | | |
| | | | Ch 2 | | 2.8 | | |
| Gate-to-Drain Charge | Q _{GD} | | Ch 1 | | 7.2 | | |
| | | | Ch 2 | | 4.0 | | |
| Plateau Voltage | V _{GP} | Ch 1 | | 3.2 | | V | |
| | | Ch 2 | | 3.3 | | | |
| Gate Resistance | R _G | | Ch 1 | | 1.2 | | Ω |
| | | | Ch 2 | | 2.1 | | |

SWITCHING CHARACTERISTICS (Note 10)

| | | | | | | | |
|---------------------|--------------|---|------|--|------|--|----|
| Turn-On Delay Time | $t_{d(ON)}$ | $V_{GS} = 4.5\text{ V}, V_{DD} = 20\text{ V}, CH1:$ $I_D = 10\text{ A}, CH2: I_D = 7\text{ A}, R_G =$ $2.5\text{ }\Omega$ | Ch 1 | | 16 | | ns |
| Rise Time | t_r | | Ch 2 | | 11.5 | | |
| | | | Ch 1 | | 22 | | |
| | | | Ch 2 | | 14 | | |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | Ch 1 | | 26 | | |
| | | | Ch 2 | | 15.5 | | |
| Fall Time | t_f | | Ch 1 | | 8.5 | | |
| | | | Ch 2 | | 3.5 | | |

DRAIN-SOURCE DIODE CHARACTERISTICS

| | | | | | | | | |
|-------------------------|-----------------|--|------------------------|------|-----|------|-----|---|
| Forward Diode Voltage | V _{SD} | V _{GS} = 0 V, CH1: I _D = 10 A, CH2: I _D = 7 A | T _J = 25°C | Ch 1 | | 0.9 | 1.2 | V |
| | | | | Ch 2 | | 0.85 | 1.2 | |
| | | | T _J = 125°C | Ch 1 | | 0.65 | | |
| | | | | Ch 2 | | 0.73 | | |
| Reverse Recovery Time | t _{RR} | V _{GS} = 0 V, dI _{SD} /dt = 100 A/μs, CH1: I _D = 10 A, CH2: I _D = 7 A | Ch 1 | | 27 | | ns | |
| Charge Time | T _a | | Ch 2 | | 17 | | | |
| | | | Ch 1 | | 14 | | | |
| | | | Ch 2 | | 11 | | | |
| Discharge Time | T _b | | Ch 1 | | 13 | | | |
| | | | Ch 2 | | 6.0 | | | |
| Reverse Recovery Charge | Q _{RR} | | Ch 1 | | 19 | | nC | |
| | | | Ch 2 | | 9.0 | | | |

9. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%

10. Switching characteristics are independent of operating junction temperatures

TYPICAL PERFORMANCE CURVES

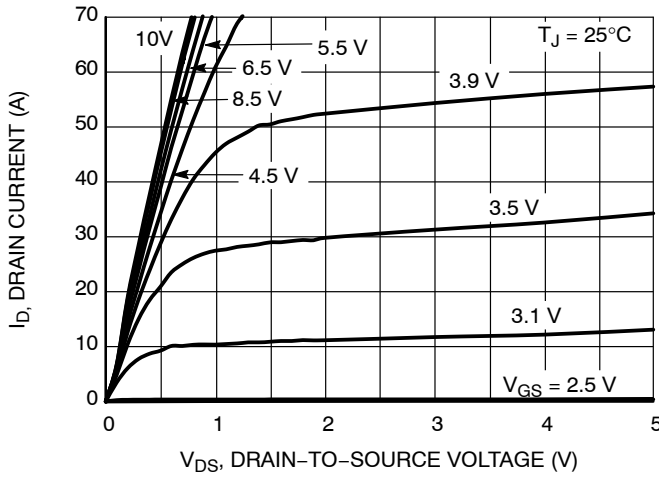


Figure 1. On-Region Characteristics - Channel 1

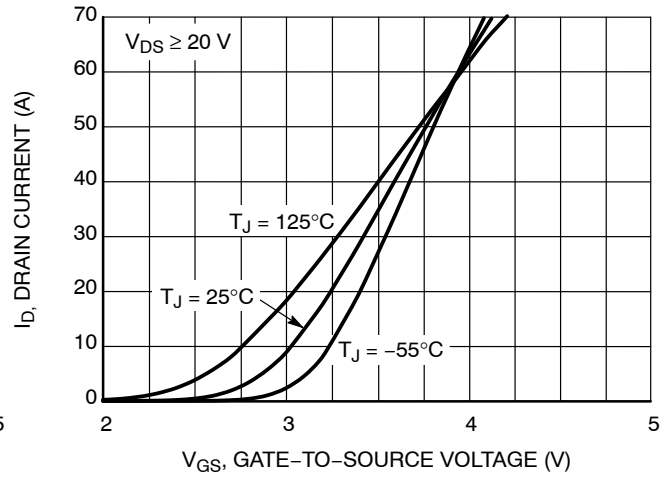


Figure 2. Transfer Characteristics - Channel 1

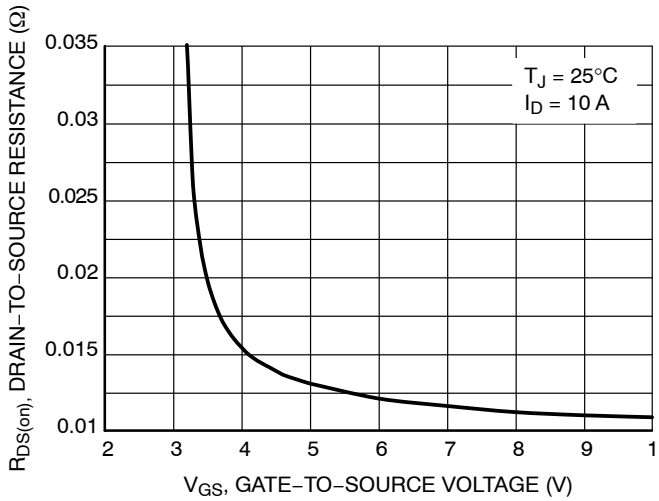


Figure 3. On-Resistance vs. Gate-to-Source Voltage - Channel 1

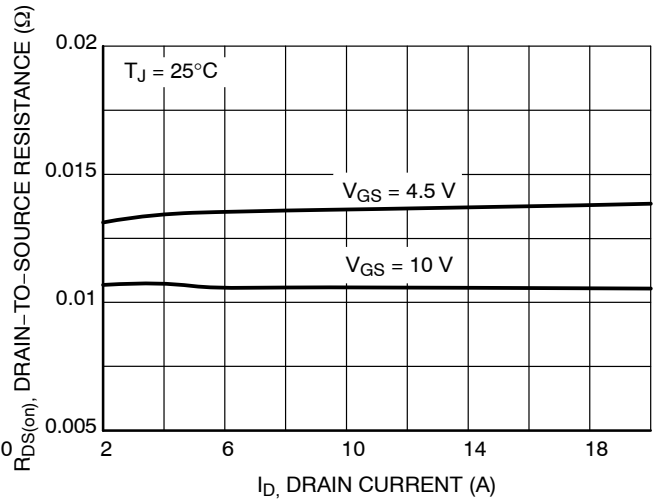


Figure 4. On-Resistance vs. Drain Current and Gate Voltage - Channel 1

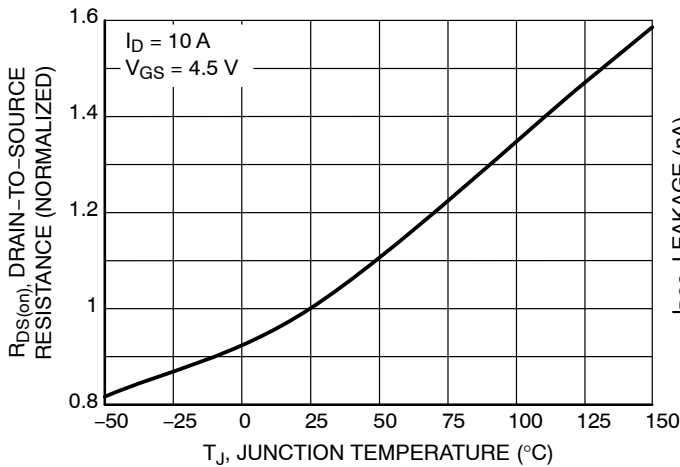


Figure 5. On-Resistance Variation with Temperature - Channel 1

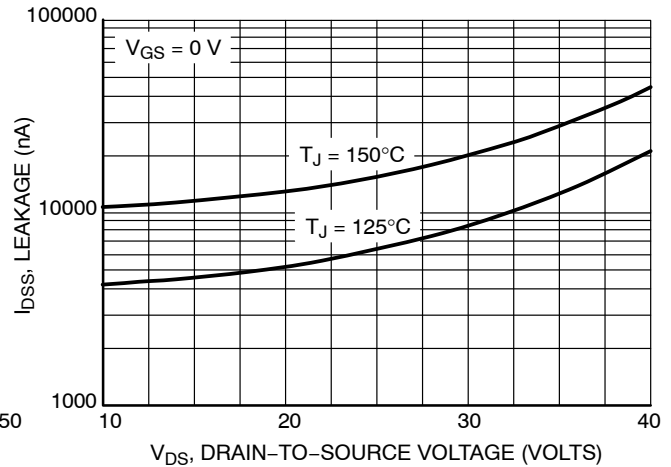


Figure 6. Drain-to-Source Leakage Current vs. Voltage - Channel 1

TYPICAL PERFORMANCE CURVES

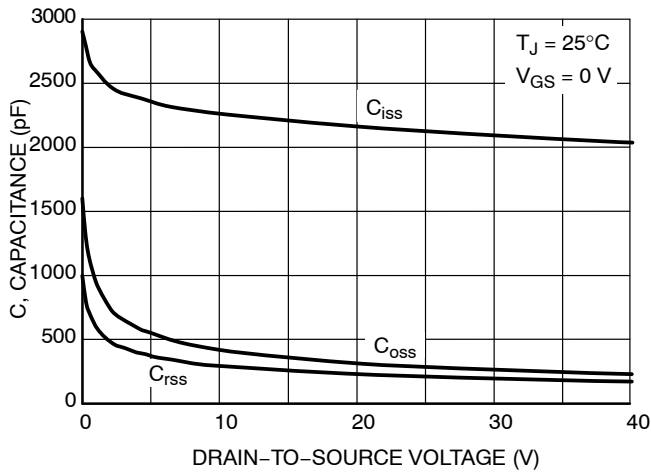


Figure 7. Capacitance Variation - Channel 1

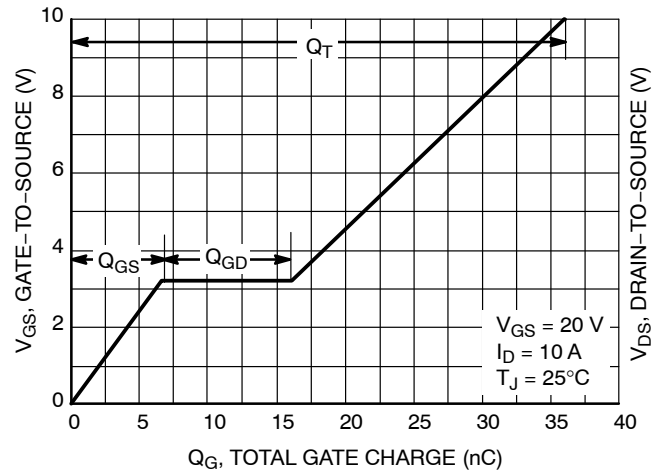


Figure 8. Gate-To-Source and Drain-To-Source Voltage vs. Total Charge - Channel 1

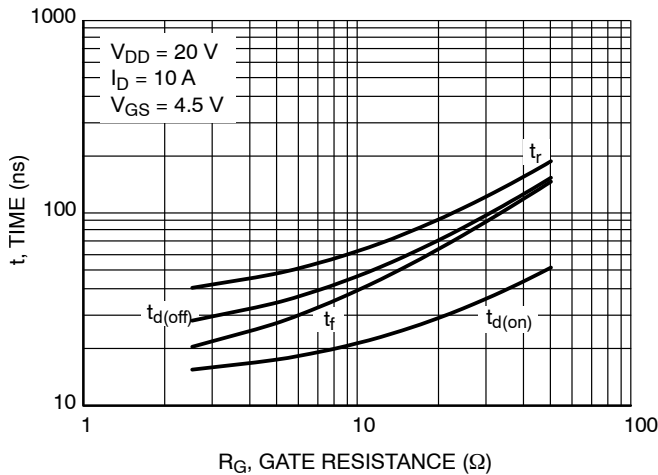


Figure 9. Resistive Switching Time Variation vs. Gate Resistance - Channel 1

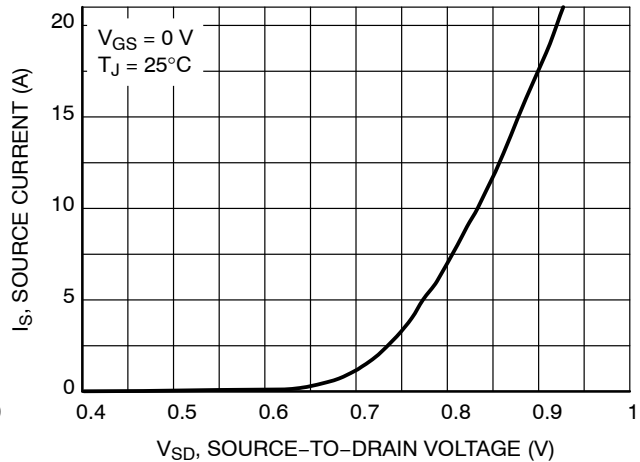


Figure 10. Diode Forward Voltage vs. Current - Channel 1

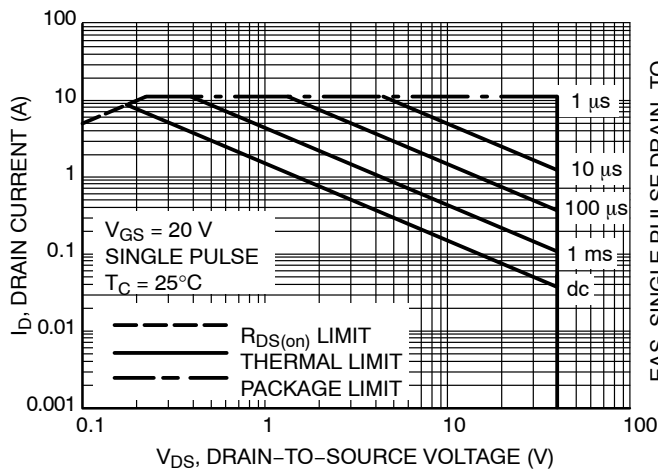


Figure 11. Maximum Rated Forward Biased Safe Operating Area - Channel 1

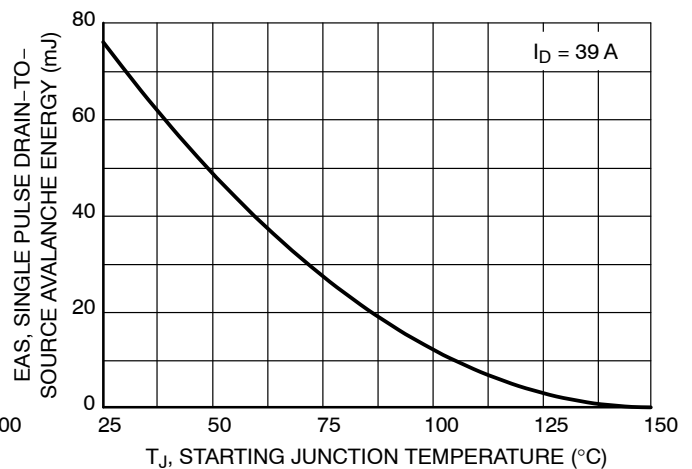


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature - Channel 1

TYPICAL PERFORMANCE CURVES

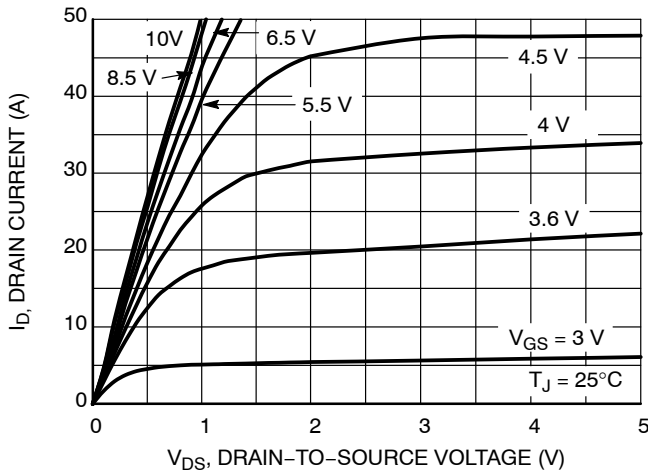


Figure 1. On-Region Characteristics - Channel 2

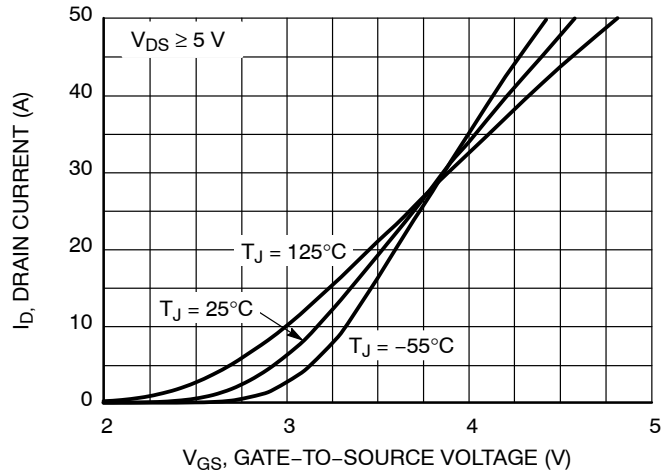


Figure 2. Transfer Characteristics - Channel 2

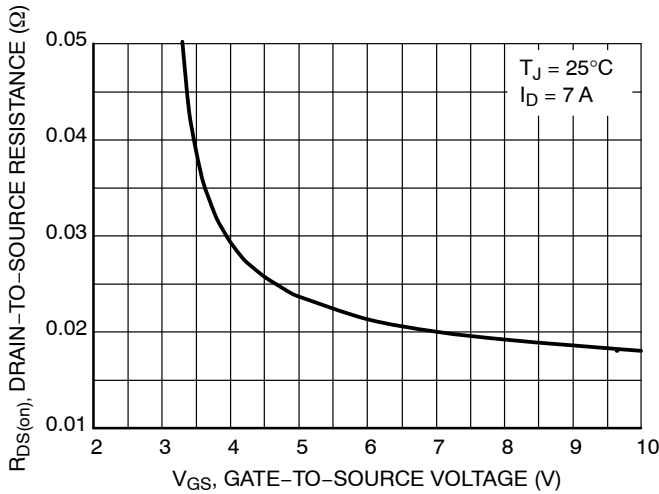


Figure 3. On-Resistance vs. Gate-to-Source Voltage - Channel 2

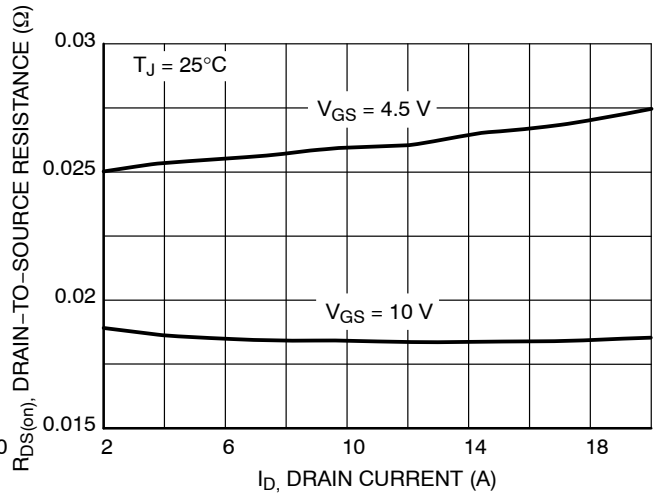


Figure 4. On-Resistance vs. Drain Current and Gate Voltage - Channel 2

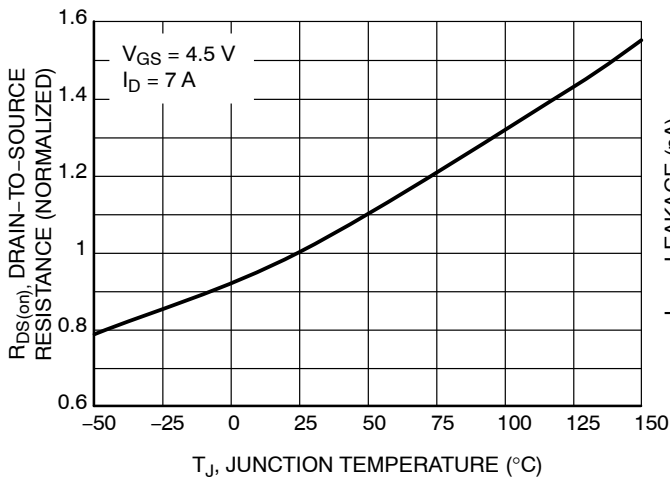


Figure 5. On-Resistance Variation with Temperature - Channel 2

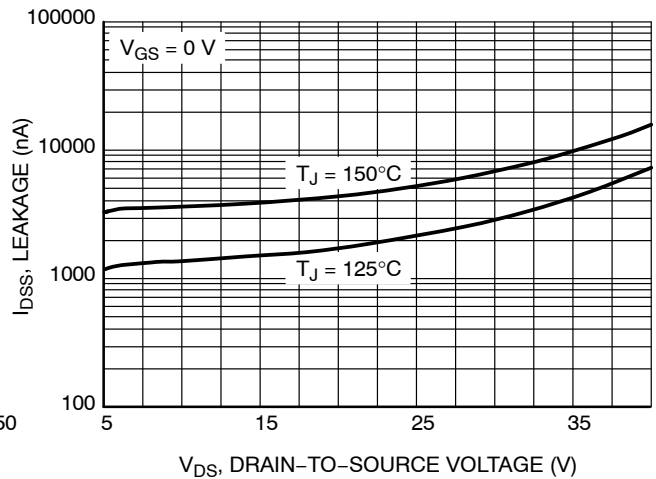


Figure 6. Drain-to-Source Leakage Current vs. Voltage - Channel 2

TYPICAL PERFORMANCE CURVES

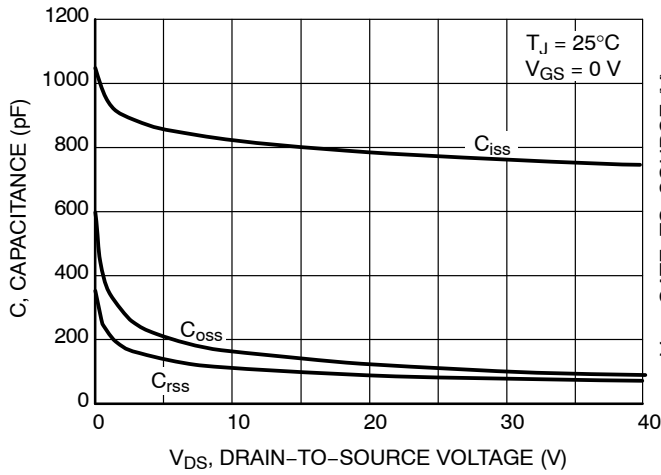


Figure 7. Capacitance Variation – Channel 2

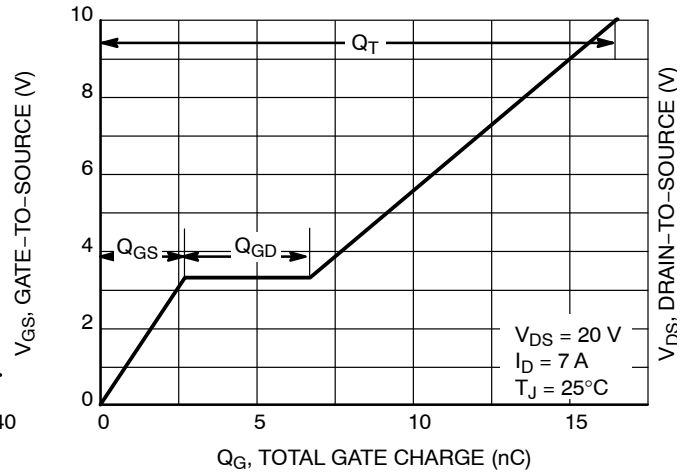


Figure 8. Gate-To-Source and Drain-To-Source Voltage vs. Total Charge

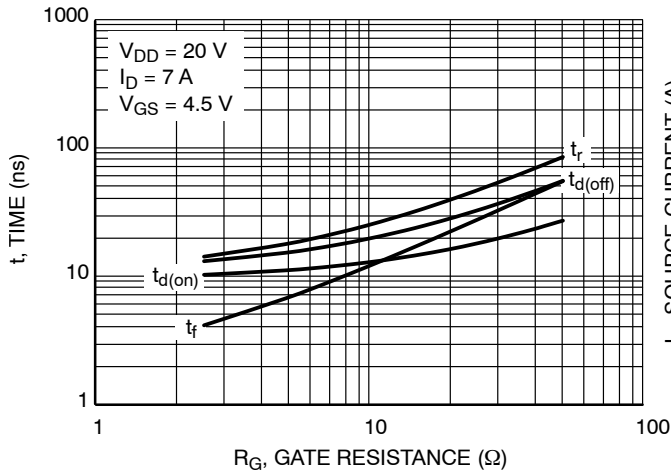


Figure 9. Resistive Switching Time Variation vs. Gate Resistance – Channel 2

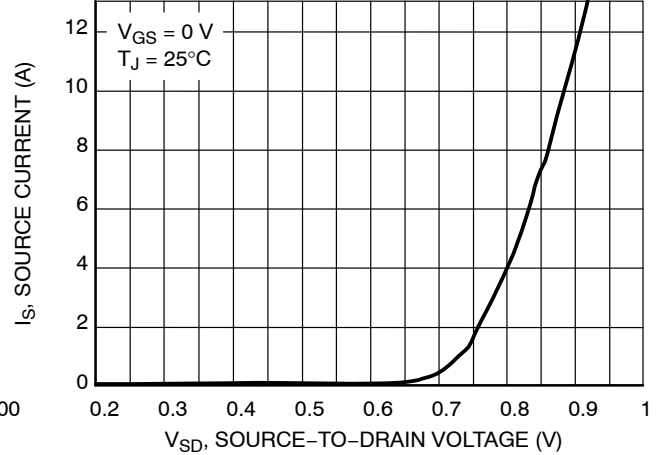


Figure 10. Diode Forward Voltage vs. Current – Channel 2

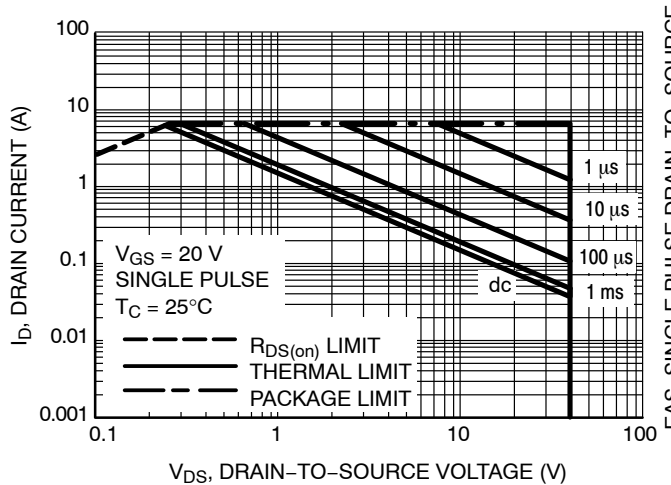


Figure 11. Maximum Rated Forward Biased Safe Operating Area – Channel 2

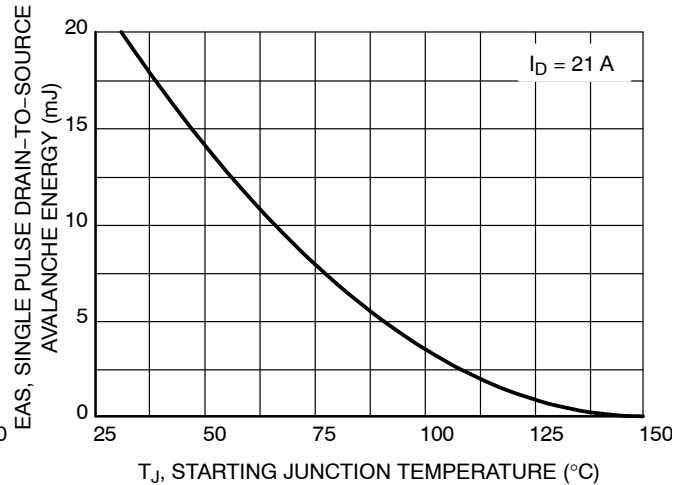


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

TYPICAL PERFORMANCE CURVES

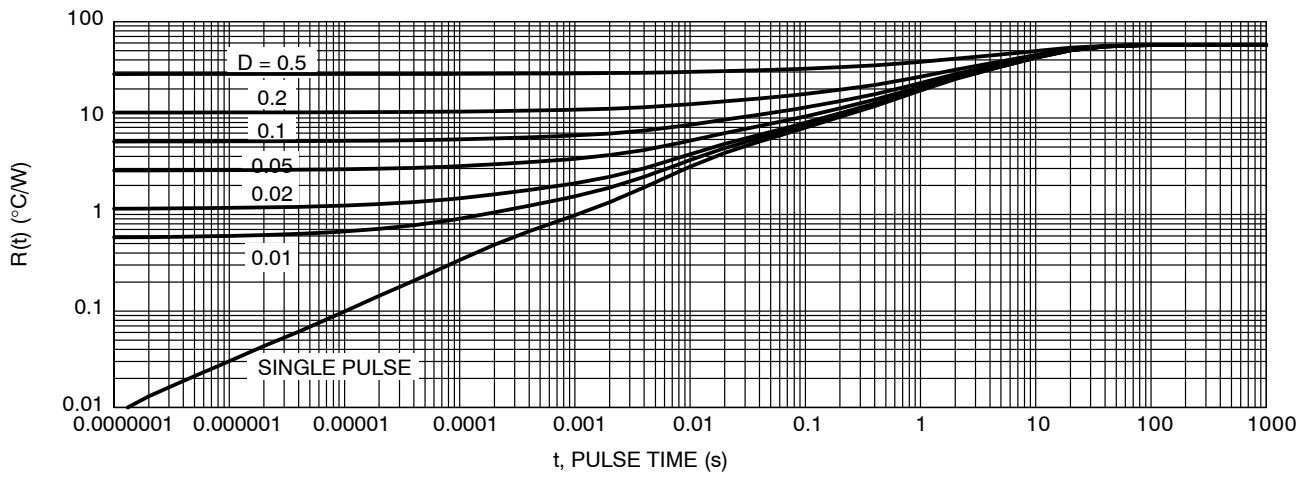


Figure 13. Thermal Response

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-8 NB
CASE 751-07
ISSUE AK

DATE 16 FEB 2011



NOTES:

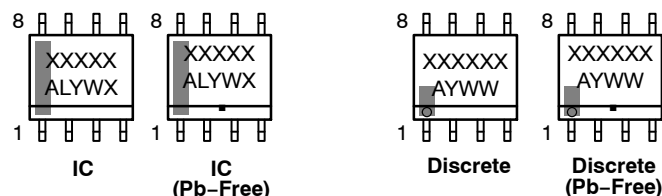
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.80 | 5.00 | 0.189 | 0.197 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.053 | 0.069 |
| D | 0.33 | 0.51 | 0.013 | 0.020 |
| G | 1.27 BSC | | 0.050 BSC | |
| H | 0.10 | 0.25 | 0.004 | 0.010 |
| J | 0.19 | 0.25 | 0.007 | 0.010 |
| K | 0.40 | 1.27 | 0.016 | 0.050 |
| M | 0° | 8° | 0° | 8° |
| N | 0.25 | 0.50 | 0.010 | 0.020 |
| S | 5.80 | 6.20 | 0.228 | 0.244 |

GENERIC MARKING DIAGRAM*



SCALE 6:1 (mm/inches)



XXXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb-Free Package

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

| | | |
|------------------|-------------|--|
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| DESCRIPTION: | SOIC-8 NB | PAGE 1 OF 2 |

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CASE 751-07
ISSUE AK

DATE 16 FEB 2011

| | | | |
|---|--|--|--|
| STYLE 1: PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER | STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1 | STYLE 3: PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1 | STYLE 4: PIN 1. ANODE 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE |
| STYLE 5: PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE | STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE | STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd | STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 8. COLLECTOR, #1 |
| STYLE 9: PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON | STYLE 10: PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND | STYLE 11: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 8. DRAIN 1 | STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN |
| STYLE 13: PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN | STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN | STYLE 15: PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON | STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 7. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1 |
| STYLE 17: PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC | STYLE 18: PIN 1. ANODE 2. ANODE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. CATHODE 8. CATHODE | STYLE 19: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. MIRROR 1 | STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN |
| STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5 6. COMMON ANODE 7. COMMON ANODE 8. CATHODE 6 | STYLE 22: PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3. COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND | STYLE 23: PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT 6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT | STYLE 24: PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE 6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE |
| STYLE 25: PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT | STYLE 26: PIN 1. GND 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC | STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN | STYLE 28: PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN |
| STYLE 29: PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1 | STYLE 30: PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1 | | |

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